



INSTITUTO GALEGO
DE FÍSICA
DE ALTAS ENERXÍAS



LHCb-VELO Upgrade II and LumiTracker – mechanics, cooling and electronics

Bhagyashree Pagare

**On behalf of the LHCb collaboration,
IGFAE, University of Santiago de Compostela, Spain**

TIPP 2.2.2026, Mumbai, India

ये है Bombay मेरी जाँ

**Most of the slides are inspired from VELO U2 workshop 2025,
Santiago de Compostela*

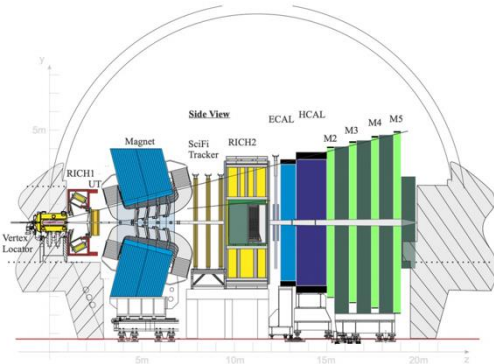
What is VELO – why so special ???

Welcome Drink

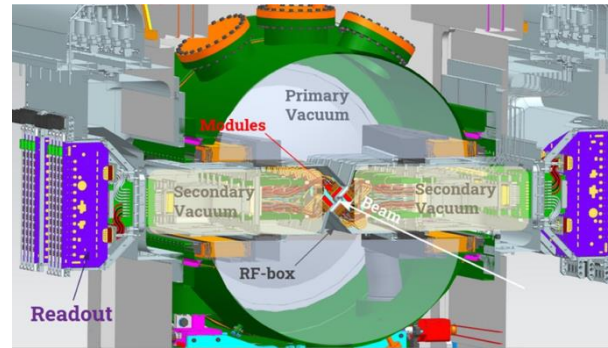


- Vertex detector close to the interaction point.
- Provides precise measurements of track positions close to the interaction point.
- 2 halves A and C side. Requires to be retracted during LHC injection.
- Operating in UHV environment. Considering LHC primary vacuum. Separated with RF foil.
- High and non-uniform radiation.

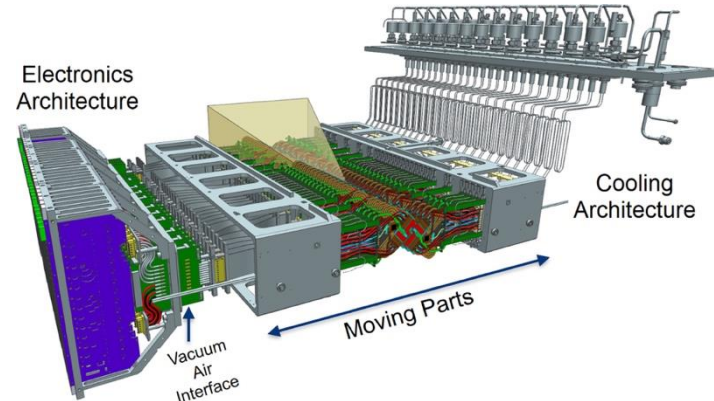
<https://iopscience.iop.org/article/10.1088/1748-0221/19/05/P05065>



TIPP 2026

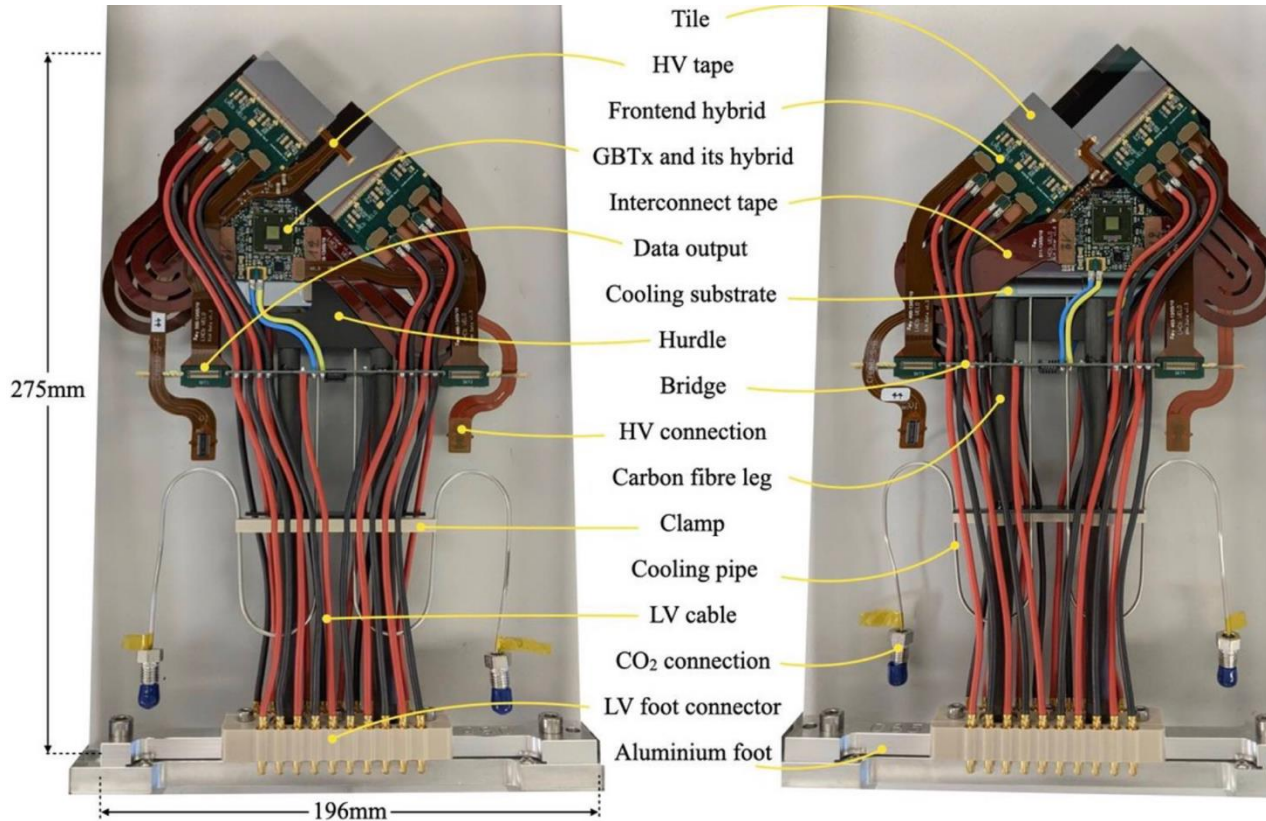


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Module design

[2024 JINST 19 P06023](#)



Evolution of the detectors because....



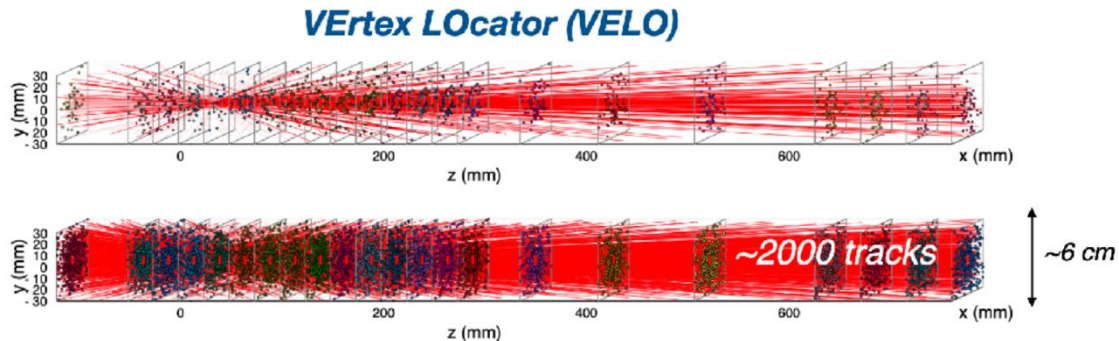
[arXiv:2208.05403](https://arxiv.org/abs/2208.05403)

- U2 target is to cope with the high mu, while keeping/improving the U1 performances.
- Timing is required to reconstruct the events, but spatial resolution is what we do physics with.
- Sensors and readout ASICs must be redesigned and more tightly synchronized.
- Electronics need to handle enormous data rates (tens of Tb/s).
- This affects mechanical layouts, cooling, power distribution, and data transmission, all of which interact with the physical design of the VELO and its support structures.

Run 3: pile-up ~5



Upgrade II: pile-up ~40



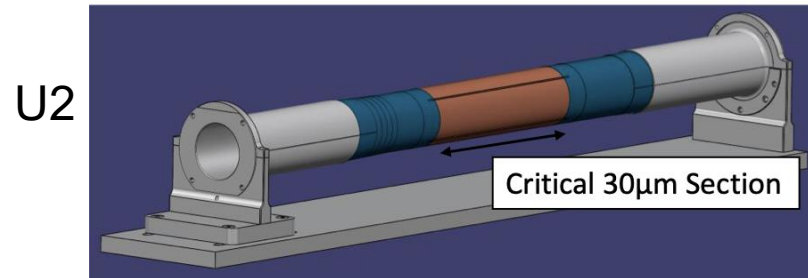
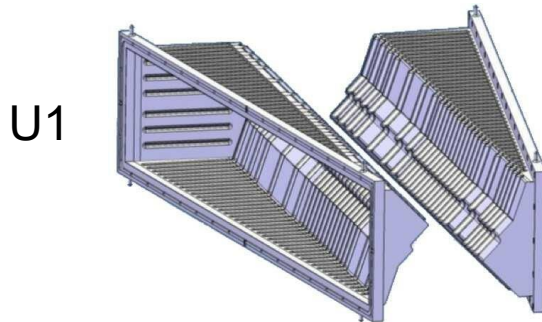
Main course 1 - Mechanics



Low Material RF shield + Vacuum

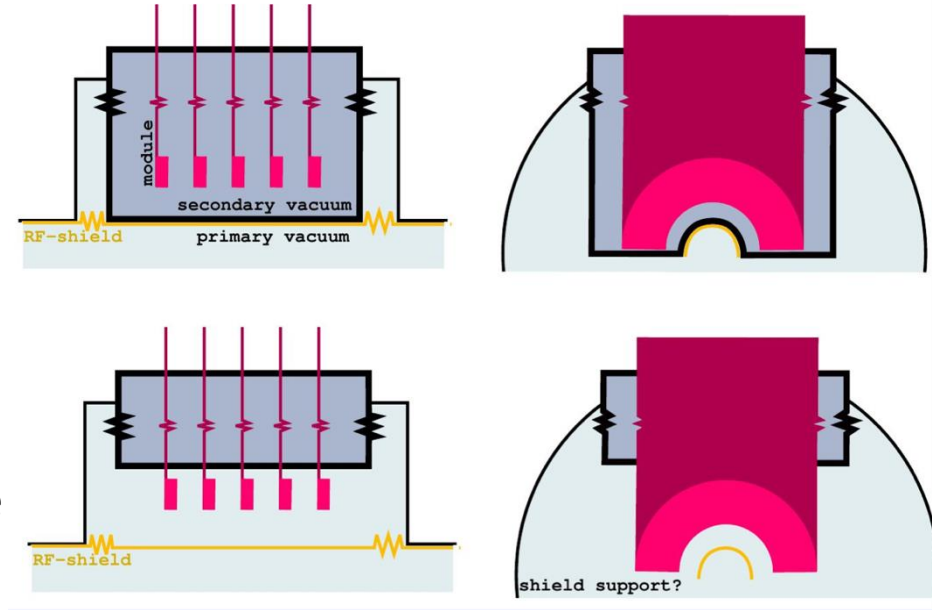
- Moving from VELO U1 corrugated design towards cylindrical RF shield :
 - Low material better performance
 - Mechanical challenge, less rigid
 - Composite design in development with ultra-low material critical section or hybrid corrugated design
- Major challenge from maintaining secondary VELO vacuum
 - Thinner material increases risk
 - Alternatively, opt for mixed-vacuum, carbon fibre mesh can meet RF requirements
 - But all components must be vacuum safe .

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The RF shield

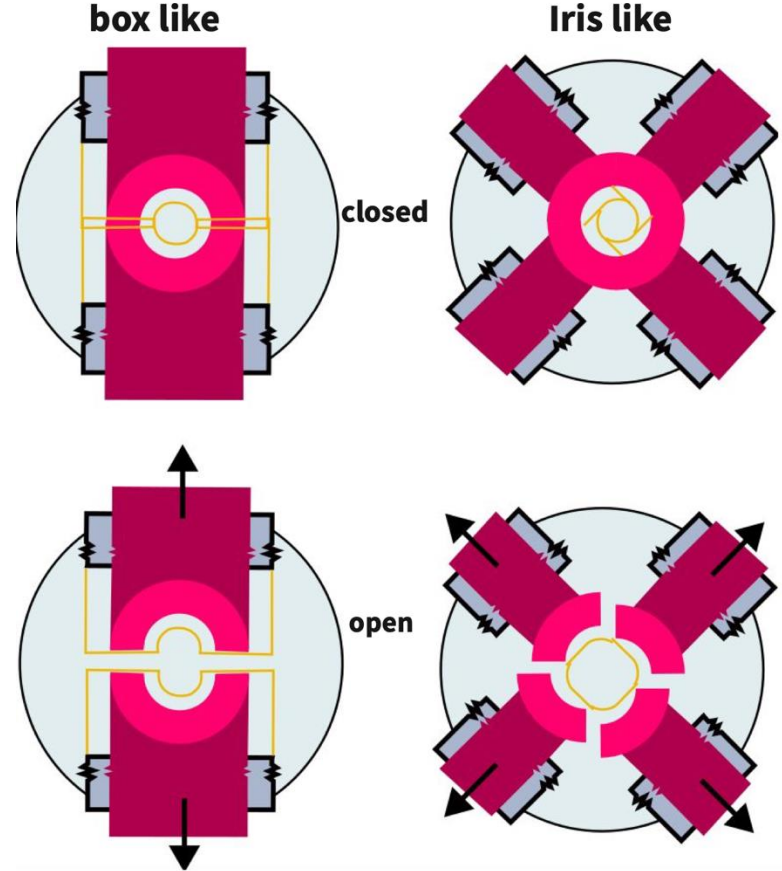
- Combined RF-shield and Vacuum barrier adds to the mechanical constraints
 - Requires to hold balancing (+/- 10mbar)
 - Lifting this requirement means the sensors live in vacuum => primary/secondary vacuum barrier in the module
 - Maximise track precision and reduce material budget due to RF foil interaction.



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RF shield

- Box like :
 - 2 flanges
 - More material in the wings
 - Current corrugated foil but with different materials
- Iris like
 - ≥ 4 flanges
 - Less material overall(?)
 - Likely lower impedance when open
 - Curving foil with support
 - Needs module to be inside.
- Performance to be checked in simulation using radiation length



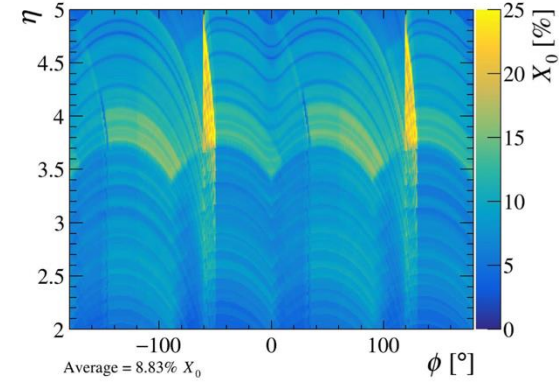
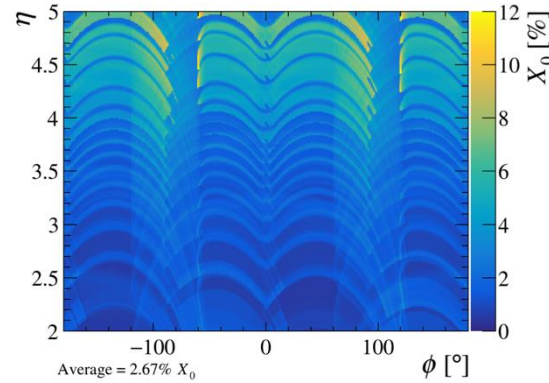
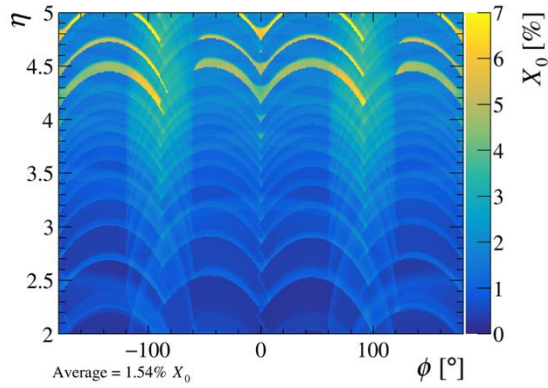
Scans of radiation lengths

Before 1st hit

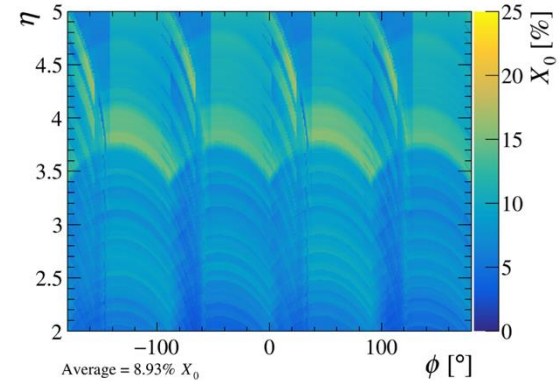
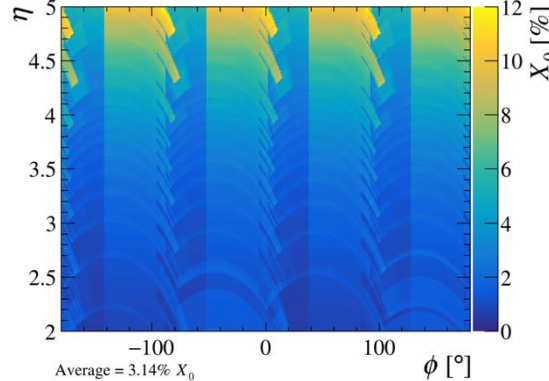
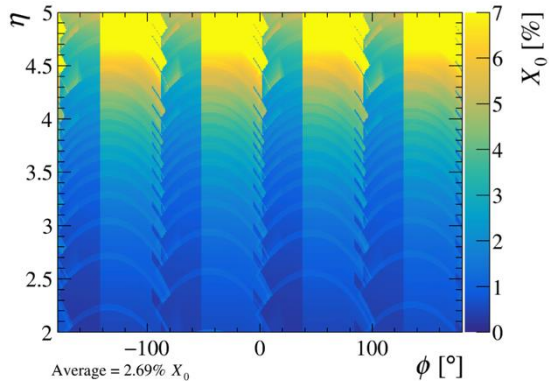
Before 2nd hit

Before last hit

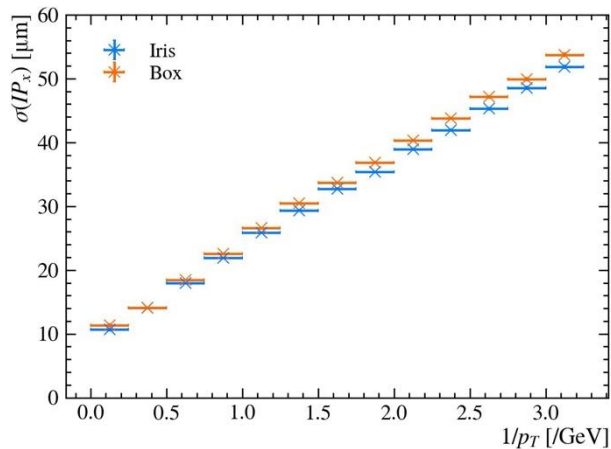
Box



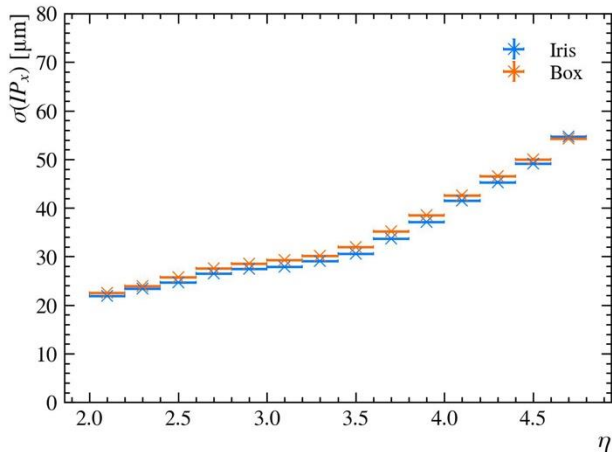
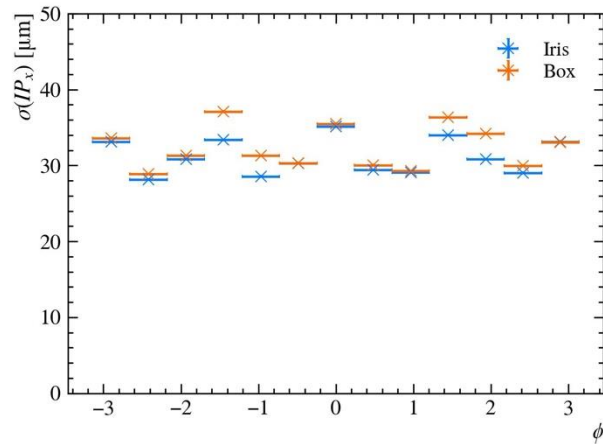
Iris



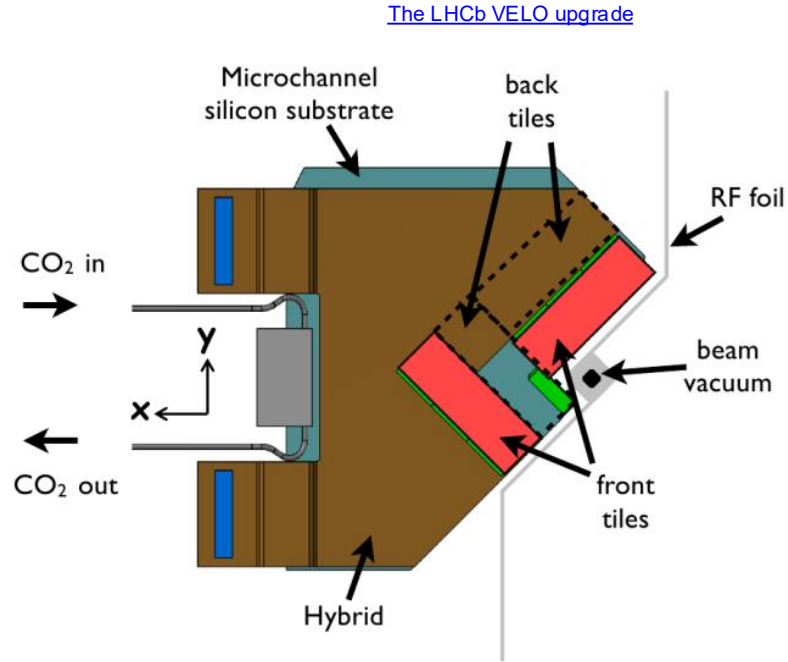
Performance



Some preliminary studies

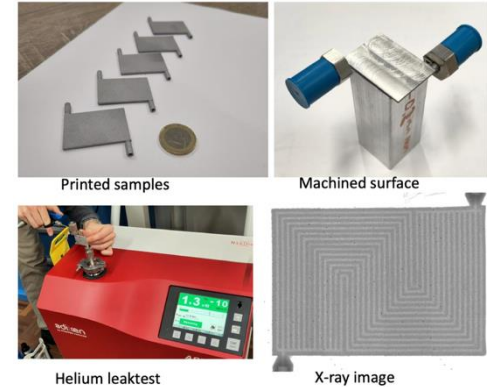


Main course 2 – Cooling and Sensors

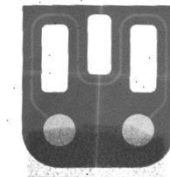
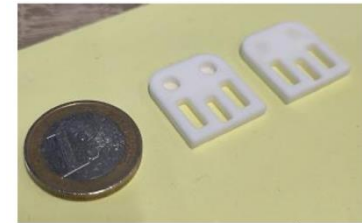


Possible cooling options

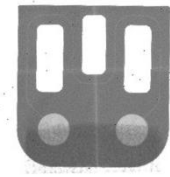
- 3D printed Aluminium : AlSi10Mg
 - High radiation length, high thermal conductivity, high CTE
 - Si 0.5% X0 equivalent thickness : $t_{AL} = 0.47\text{mm}$
 - Size: 40mm x 27mm x 1.5mm
 - 11 parallel channels size 0.8 x 0.5mm
 - Wall thickness: 0.5mm
 - Less production time and cheap cost for 3D printing
- 3D printed Ceramics
 - High radiation length, high thermal conductivity, CTE close to silicon
 - Si 0.5% X0 equivalent thickness: $t_{AlN} = 0.45\text{ mm}$, $t_{Al_2O_3} = 0.37\text{ mm}$
 - Outer dimensions: 20mm x 20mm x 2.5mm



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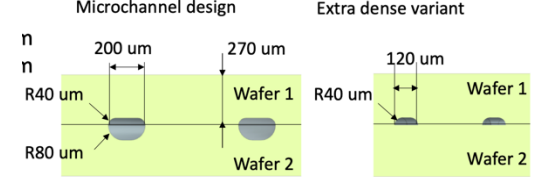
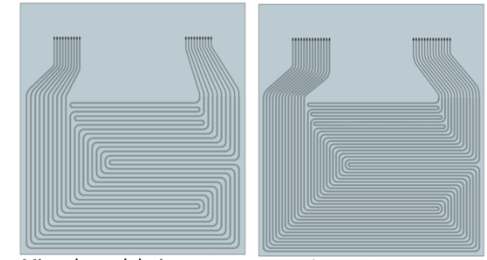
X-ray: $\square 0,37\text{ mm}$ channels



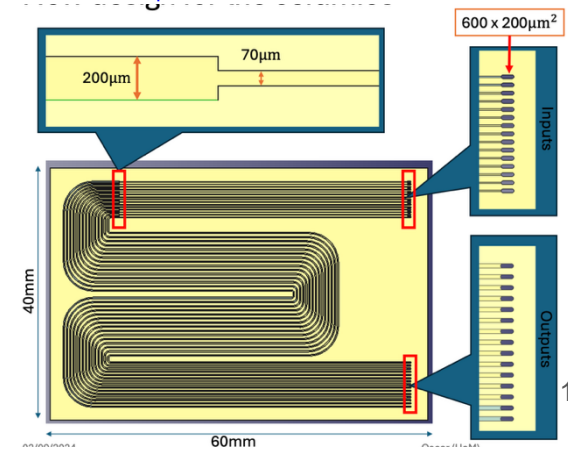
X-ray: $\square 0,2\text{ mm}$ channels

Possible cooling options

- Borosilicate glass
 - High radiation length, low thermal conductivity, low CTE
 - Microchannel design
 - 10 x Channels: 200um x 120um
 - Pitch: 1000um
 - Restriction: 120um x 40um
 - Variant – Extra dense
 - 14 Channel: 200um x 120um
 - Pitch: 700um
- Ceramic microchannels
 - Robutness and reliability
 - Possible to embed conductive layers in between ceramics layers and metalize the surface
 - Potential to integrate electronics or high conductivity elements
 - Mechanically robust and compatible with UHV

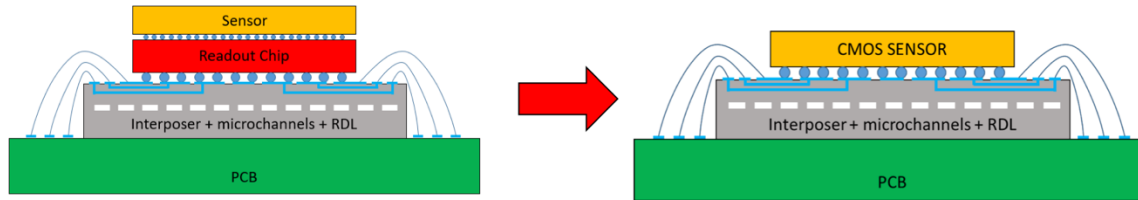


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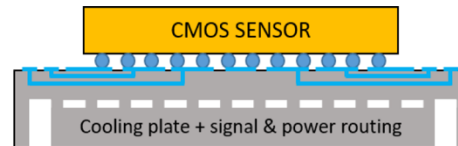


Possible cooling options

- Silicon microchannels
- Heterogeneous integration: microchannels embedded in functional silicon interposers with integrated signal and power routing
 - Combining the cooling capabilities with the electrical connection of the CMOS detector
 - For signal and power routing -> Redistribution Layer (RDL)



- Also interposer for mechanical support: “All.silicon” ladder



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In the end final choice will be made on cooling performance and thermal stability

3D sensors for VELO U2

Advantages

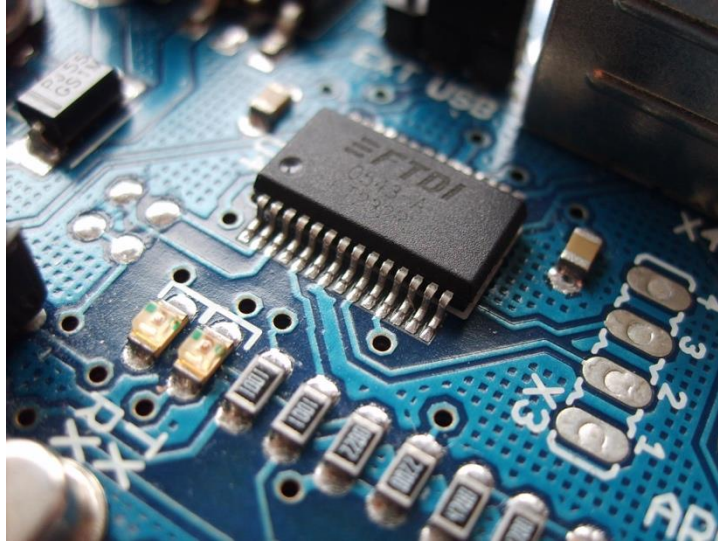
- Low depletion voltage (low power diss.)
- Excellent radiation hardness ($\geq 10^{16}$ neq/cm²)
- Tolerant to high bias even in non-irradiated zones
- Short charge collection distance:
 - Fast response rise
 - Less trapping probability after irradiation
- Goals
 - ≤ 50 ps timing and $\geq 99\%$ efficiency
 - Low capacitance and ASIC compatibility
- Lateral charge drift -> cell “shielding” effect:
 - Lower charge sharing
 - Low sensitivity to magnetic field

Disadvantages

- Non uniform spatial response (electrodes and low field regions)
- Higher capacitance with respect to planar (around 3-5x for 200um thickness)
- Complicated technology (cost, yield)

See talk by [Morag Williams](#)

Main course 3 – Electronics



Data Readout

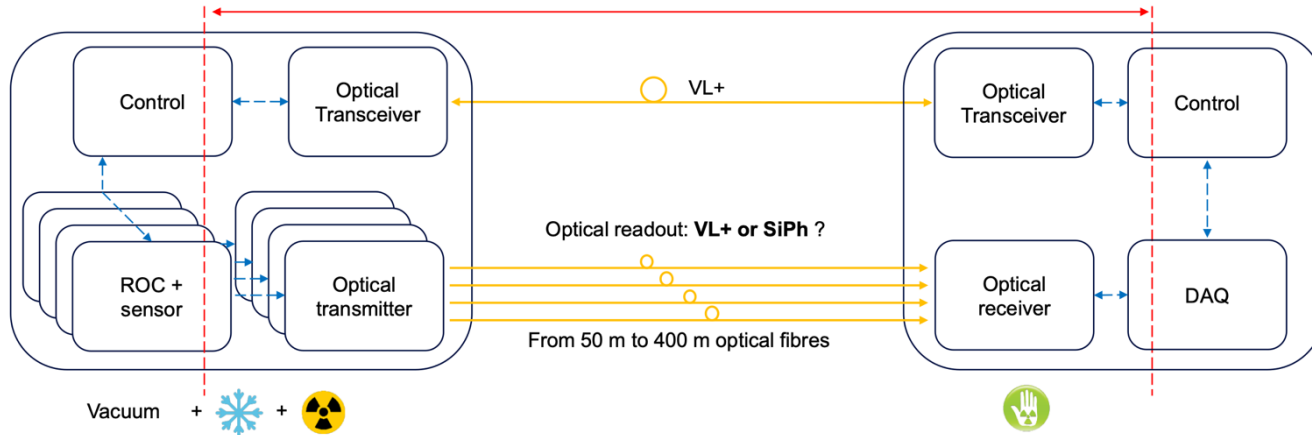
From detector...



?



... to back end



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- Fibre optic link between front-end and back-end
- Control and timing using the Versatile Link + (VTRx+) and IpGBT
- Detector readout based on VTRx+ or Silicon Photonics (SiPh) optical transmitter

Silicon Photonics

- Photonic Integrated Circuits (PICs)
 - Chiplet fabricated using CMOS process
 - Fiber couplers, optical waveguides, modulators, photodiodes
 - Radiation tolerant
- Wavelength division multiplexing (WDM)
 - Lane (optical channel) : 25 Gbps
 - Fibre : 100 Gbps
- Laser sits outside of radiation environment
 - Wavelength 1300 nm
 - Transparent window for silicon
- Low power / Low mass

Versatile Link PLUS

- A bi-directional optical transceiver for optical links
 - Discrete opto-electronic components
 - Radiation tolerant,
 - low mass, low power.
- No WDM. Single wavelength
 - ~10Gbps
 - One lane per fibre
- Laser integrated inside
 - ~1310 nm
- Modules need to be kept in secondary vacuum.

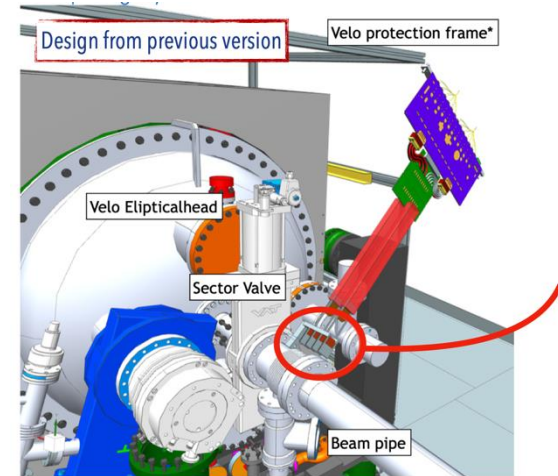
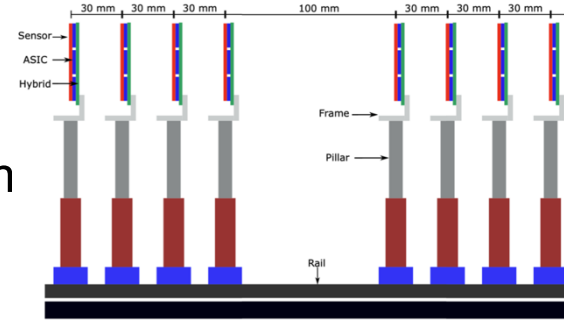
Main course 4 – LumiTracker and ALADDIN



LumiTracker --- based on VELO U2 developments

- Mini-telescope upstream of VELO
- Based on track counting
- 6-8 hybrid silicon planes arranged in two arms
- Planes layout optimised for tracks from luminous region
- Rotation around z between 30-60 degrees for better mechanical integration
- Full length around 35cm
- Provide real-time luminosity measurement per bunch
 - Beneficial that its always closed
 - Similar precision as VELO
- Integration into the LHCb global event stream
- Luminous region monitoring
- ALADDIN experiment - project under study based on VELO U2 developments. - Aims to measure the dipole moments of charmed baryons.

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The Desert : Summary and a look into the future

- Different RF geometries are being looked at
 - Box-like and Iris-like
- Different cooling options are being studied
 - Silicon microchannels, 3D aluminium, 3D ceramics, Ceramic microchannel, Borosilicate glass.
- Fibre-link options were discussed
 - Silicon photonics and VTRx
- Prototypes like LumiTracker and experiment like ALLADIN are being pursued

